

In the claims:

Cancel Claim 1.

Claim 2 (currently amended) A tin-silver based lead-free solder containing 0.3 to 1% of zinc further containing 8 to 10% by weight of indium (In) added thereto.

Claim 3 (cancelled).

Cancel Claim 4.

Claim 5 (currently amended) A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 1-2.

Claim 6 (previously presented) The joint structure of claim 5, wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 7 (previously presented) The joint structure of claim 6, wherein said electroless-plating layer is a Ni-P plating.

Cancel Claim 8.

Claim 9 (currently amended)

of silver.

A solder of claim 2 containing 3 to 3.5% by weight

Cancel Claims 10 to 16.